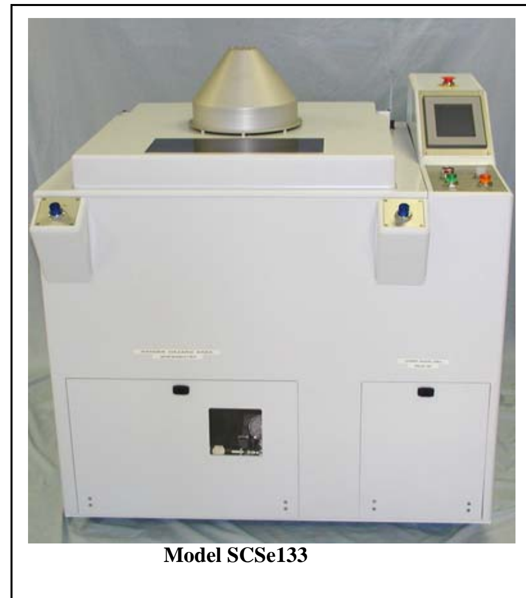
ULTRA t Equipment — Model SCS*e*133

DESCRIPTION

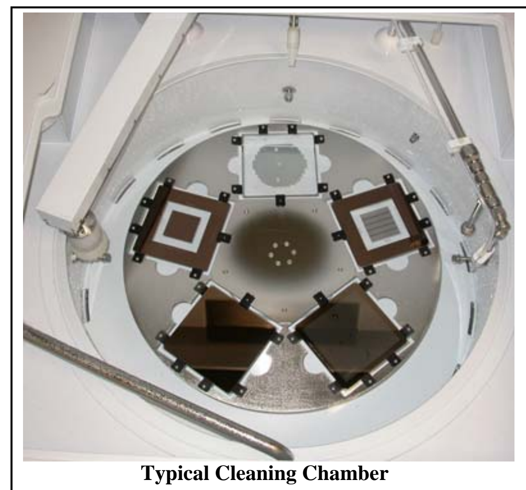
The ***highly efficient*** Model SCS*e*133 is the ideal solution for submicron cleaning of Photomasks, Wafers and Substrates. The ***very reliable*** and ***cost effective*** system utilizes ***proven*** assortment of cleaning technologies. The SCSe133 can be configured with several different cleaning options form High Pressure DI, Atomizing Mist Nozzle, Brushes, Megasonic Pies and Nozzles, and much more. The Rapid and Effective Drying technique combines Variable Spin Speeds optional Heated DI, Nitrogen Assist or Heat Lamp. The SCS*e*133 has a Microprocessor Controller allowing variable process parameters and retention of up to (10) ten process programs in memory.



Model SCSe133

FEATURES:

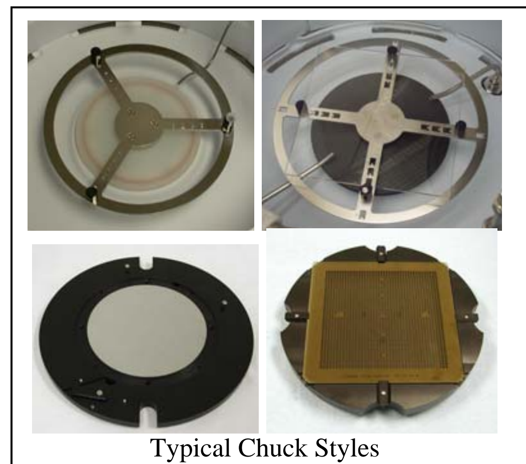
- Up to Twenty One (21) Inch Diameter Substrate Compatibility
- Main Spindle Assembly having Servo Motor
- Adjustable Arm Speed and Travel Positions.
- Radially Exhausted Chamber for Maximum Laminar Flow.
- Stand-alone Polypropylene Cabinet.
- Microprocessor Control Capable of Retaining Ten (10) Programs in Memory
- Built in Safety Interlocks.
- Push Button Lid Open/Close.
- Touch Screen Graphic User Interface (GUI) with Ease of Programming & Security Lockouts and On-Screen Error Reporting.
- Maximum Capability of Four Arms.



Typical Cleaning Chamber

OPTIONS: ***Up to Four Oscillating Arms***

- Various sizes of vacuum and edge-grip chucks for Wafers, Photomasks, and other Substrates
- Adjustable Self Cleaning Brush Assembly
- N_2 Drying Assist with 0.02 µm Filtration
- Fixed or Oscillating Low Pressure Dispenses
- Surfactant or Photoresist Dispense Canisters
- Chamber Rinse and/or Chamber Exhaust Assembly
- 0.2 µm Filtration for Low Pressure Dispenses
- D.I. Water Heater and Dispenses
- Oscillating Megasonic DI Water Dispense Arm



Typical Chuck Styles

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